flow PIM 0 3rd gen — 1200 V / 8 A

Features

- 2 Clips housing in 12 and 17mm height
- Trench Fieldstop Technology IGBT4
- Optional w/o BRC

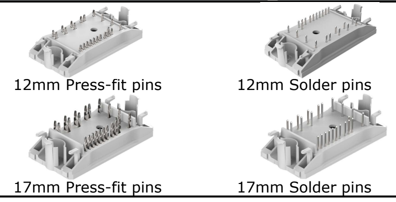
Target Applications

- Industrial Drives
- Embedded Generation

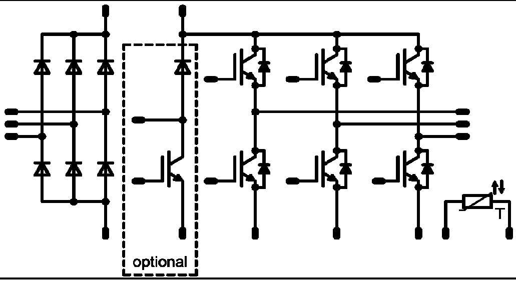
Types

- V23990-P849-A48(Y)-PM
- V23990-P849-A49(Y)-PM
- V23990-P849-C48(Y)-PM
- V23990-P849-C49(Y)-PM

flow PIM 0 3rd gen



Schematic



Maximum Ratings

T_j=25°C, unless otherwise specified

Parameter	Symbol	Condition		Value	Unit
Input Rectifier Diode					
Repetitive peak reverse voltage	V_{RRM}			1600	V
DC forward current	I_{FAV}	$T_j=T_j$max	T_h=80°C T_c=80°C	27 30	A
Surge forward current	I_{FSM}	t_p=10ms	T_j=25°C	220	A
I2t-value	I^2t	t_p=10ms	T_j=25°C	200	A^2s
Power dissipation	P_{tot}	$T_j=T_j$max	T_h=80°C T_c=80°C	33 50	W
Maximum Junction Temperature	T_{jmax}			150	°C
Inverter Transistor					
Collector-emitter break down voltage	V_{CE}			1200	V
DC collector current	I_C	$T_j=T_j$max	T_h=80°C T_c=80°C	13 16	A
Pulsed collector current	I_{CRM}	t_p limited by $T_j$max		24	A
Turn off safe operating area		VCE ≤ 1200V, Tj ≤ Top max		16	A
Power dissipation	P_{tot}	Tj=Tjmax	T_h=80°C T_c=80°C	44 67	W
Gate-emitter peak voltage	V_{GE}			±20	V
Short circuit ratings	t_{SC} V_{CC}	T_j≤150°C V_{GE}=15V		10 800	μs V
Maximum Junction Temperature	T_{jmax}			175	°C

Maximum Ratings

T_j=25°C, unless otherwise specified

Parameter	Symbol	Condition		Value	Unit
Inverter Diode					
Peak Repetitive Reverse Voltage	V_{RRM}			1200	V
DC forward current	I_F	T_j=$T_j$max	T_h=80°C T_c=80°C	15 20	A
Repetitive peak forward current	I_{FRM}	t_p limited by $T_j$max		20	A
Power dissipation	P_{tot}	T_j=$T_j$max	T_h=80°C T_c=80°C	35 54	W
Maximum Junction Temperature	T_{jmax}			175	°C
Brake Transistor					
Collector-emitter break down voltage	V_{CE}			1200	V
DC collector current	I_C	T_j=$T_j$max	T_h=80°C T_c=80°C	8 10	A
Pulsed collector current	I_{CRM}	t_p limited by $T_j$max		12	A
Turn off safe operating area		VCE ≤ 1200V, Tj ≤ Top max		8	A
Power dissipation	P_{tot}	T_j=$T_j$max	T_h=80°C T_c=80°C	32 49	W
Gate-emitter peak voltage	V_{GE}			±20	V
Short circuit ratings	t_{SC} V_{CC}	T_j≤150°C V_{GE}=15V		10 360	μs V
Maximum Junction Temperature	T_{jmax}			175	°C
Brake Diode					
Peak Repetitive Reverse Voltage	V_{RRM}			1200	V
DC forward current	I_F	T_j=$T_j$max	T_h=80°C T_c=80°C	6 6	A
Repetitive peak forward current	I_{FRM}	t_p limited by $T_j$max		6	A
Power dissipation	P_{tot}	T_j=$T_j$max	T_h=80°C T_c=80°C	18 27	W
Maximum Junction Temperature	T_{jmax}			150	°C
Thermal Properties					
Storage temperature	T_{stg}			-40…+125	°C
Operation temperature under switching condition	T_{op}			-40…+(Tjmax - 25)	°C
Insulation Properties					
Insulation voltage	V_{is}	t=2s	DC voltage	4000	V
Creepage distance				min 12,7	mm
Clearance		12mm solder pin/12mm Press-fit pin/ 17mm housing		9,7/9,48/>12,7	mm
Comparative tracking index	CTI			>200	

Characteristic Values

Parameter	Symbol	Conditions	V_{GE} [V] or V_{GS} [V]	V_r [V] or V_{CE} [V] or V_{DS} [V]	I_C [A] or I_F [A] or I_D [A]	T_j	Value Min	Value Typ	Value Max	Unit
Input Rectifier Diode										
Forward voltage	V_F				30	Tj=25°C Tj=125°C		1,2 1,17	1,8	V
Threshold voltage (for power loss calc. only)	V_{to}				30	Tj=25°C Tj=125°C		0,93 0,8		V
Slope resistance (for power loss calc. only)	r_t				30	Tj=25°C Tj=125°C		11 15		mΩ
Reverse current	I_r			1500		Tj=25°C Tj=125°C			0,1	mA
Thermal resistance chip to heatsink	$R_{th(j-s)}$	Thermal grease thickness≤50um λ = 1 W/mK						2,13		K/W
Thermal resistance chip to heatsink	$R_{th(j-s)}$	Phase-Change Material λ=3,4W/mK						1,84		K/W
Inverter Transistor										
Gate emitter threshold voltage	$V_{GE(th)}$	$V_{CE}=V_{GE}$			0,0003	Tj=25°C Tj=125°C	5	5,8	6,5	V
Collector-emitter saturation voltage	V_{CEsat}				8	Tj=25°C Tj=125°C	1,6	1,87 2,20	2,35	V
Collector-emitter cut-off current incl. Diode	I_{CES}		0	1200		Tj=25°C Tj=125°C			0,05	mA
Gate-emitter leakage current	I_{GES}		20	0		Tj=25°C Tj=125°C			200	nA
Integrated Gate resistor	R_{gint}							none		Ω
Turn-on delay time	$t_{d(on)}$	Rgoff=32 Ω Rgon=32 Ω	15	600	8	Tj=25°C Tj=125°C		71 71		ns
Rise time	t_r					Tj=25°C Tj=125°C		19 23		
Turn-off delay time	$t_{d(off)}$					Tj=25°C Tj=125°C		194 236		
Fall time	t_f					Tj=25°C Tj=125°C		79 108		
Turn-on energy loss	E_{on}					Tj=25°C Tj=125°C		0,50 0,75		mWs
Turn-off energy loss	E_{off}					Tj=25°C Tj=125°C		0,43 0,62		
Input capacitance	C_{ies}	f=1MHz	0	25		Tj=25°C		490		pF
Output capacitance	C_{oss}							50		
Reverse transfer capacitance	C_{rss}							30		
Gate charge	Q_G	Vcc=960V	±15		8	Tj=25°C		53		nC
Thermal resistance chip to heatsink	$R_{th(j-s)}$	Thermal grease thickness≤50um λ = 1 W/mK						2,16		K/W
Thermal resistance chip to heatsink	$R_{th(j-s)}$	Phase-Change Material λ=3,4W/mK						1,86		K/W
Inverter Diode										
Diode forward voltage	V_F				10	Tj=25°C Tj=125°C	1,35	1,70 1,66	2,2	V
Peak reverse recovery current	I_{RRM}	Rgon=32 Ω				Tj=25°C Tj=125°C		8,47 9,88		A
Reverse recovery time	t_{rr}					Tj=25°C Tj=125°C		251 383		ns
Reverse recovered charge	Q_{rr}					Tj=25°C Tj=125°C		0,89 1,57		μC
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					Tj=25°C Tj=125°C		84 69		A/μs
Reverse recovered energy	E_{rec}					Tj=25°C Tj=125°C		0,34 0,63		mWs
Thermal resistance chip to heatsink	$R_{th(j-s)}$	Thermal grease thickness≤50um λ = 1 W/mK						2,68		K/W
Thermal resistance chip to heatsink	$R_{th(j-s)}$	Phase-Change Material λ=3,4W/mK						2,33		K/W

Characteristic Values

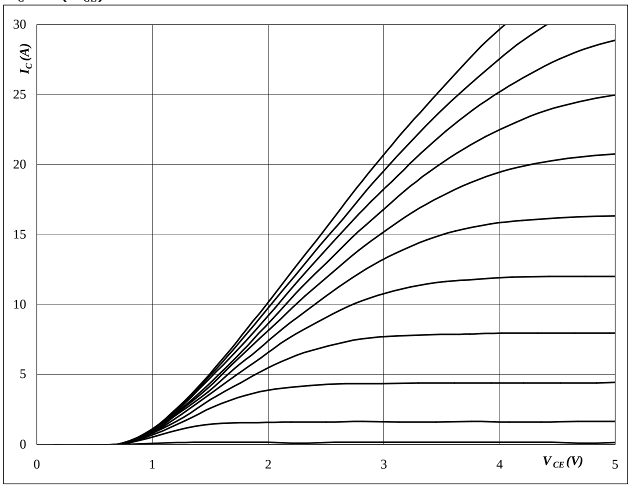
Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] or V_{GS} [V]	V_r [V] or V_{CE} [V] or V_{DS} [V]	I_C [A] or I_F [A] or I_D [A]	T_j	Min	Typ	Max	
Brake Transistor										
Gate emitter threshold voltage	$V_{GE(th)}$	$V_{CE}=V_{GE}$			0,00015	Tj=25°C Tj=125°C	5	5,8	6,5	V
Collector-emitter saturation voltage	V_{CEsat}		15		4	Tj=25°C Tj=125°C	1,6	1,96 2,17	2,2	V
Collector-emitter cut-off incl diode	I_{CES}		0	1200		Tj=25°C Tj=125°C			0,05	mA
Gate-emitter leakage current	I_{GES}		20	0		Tj=25°C Tj=125°C			200	nA
Integrated Gate resistor	R_{gint}							none		Ω
Turn-on delay time	$t_{d(on)}$					Tj=25°C Tj=125°C		93 90		
Rise time	t_r					Tj=25°C Tj=125°C		19 24		
Turn-off delay time	$t_{d(off)}$	Rgoff=64 Ω Rgon=64 Ω	15	600	4	Tj=25°C Tj=125°C		184 226		ns
Fall time	t_f					Tj=25°C Tj=125°C		71 99		
Turn-on energy loss	E_{on}					Tj=25°C Tj=125°C		0,25 0,34		mWs
Turn-off energy loss	E_{off}					Tj=25°C Tj=125°C		0,22 0,30		
Input capacitance	C_{ies}							250		
Output capacitance	C_{oss}	f=1MHz	0	25		Tj=25°C		25		pF
Reverse transfer capacitance	C_{rss}							15		
Gate charge	Q_G		15	960	4	Tj=25°C		25		nC
Thermal resistance chip to heatsink	$R_{th(j-s)}$	Thermal grease thickness≤50um λ = 1 W/mK						2,93		K/W
Thermal resistance chip to heatsink	$R_{th(j-s)}$	Phase-Change Material λ=3,4W/mK						2,55		K/W
Brake Diode										
Diode forward voltage	V_F				4	Tj=25°C Tj=125°C	1	1,91 1,84	2,35	V
Reverse leakage current	I_r			1200		Tj=25°C Tj=125°C			250	µA
Peak reverse recovery current	I_{RRM}					Tj=25°C Tj=125°C		4,22 4,65		A
Reverse recovery time	t_{rr}	Rgon=64 Ω Rgon=64 Ω				Tj=25°C Tj=125°C		268 446		ns
Reverse recovered charge	Q_{rr}					Tj=25°C Tj=125°C		0,44 0,44		µC
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					Tj=25°C Tj=125°C		44 40		A/µs
Reverse recovery energy	E_{rec}					Tj=25°C Tj=125°C		0,18 0,32		mWs
Thermal resistance chip to heatsink	$R_{th(j-s)}$	Thermal grease thickness≤50um λ = 1 W/mK						3,98		K/W
Thermal resistance chip to heatsink	$R_{th(j-s)}$	Phase-Change Material λ=3,4W/mK						3,49		K/W
Thermistor										
Rated resistance	R					T=25°C		22000		Ω
Deviation of R100	$\Delta_{R/R}$	R100=1486 Ω				T=100°C	-5		5	%
Power dissipation	P					T=25°C		210		mW
Power dissipation constant						T=25°C		3,5		mW/K
B-value	$B_{(25/50)}$	Tol. ±3%				T=25°C		3940		K
B-value	$B_{(25/100)}$	Tol. ±3%				T=25°C		4000		K
Vincotech NTC Reference									A	

Output Inverter

Figure 1 Output inverter IGBT

Typical output characteristics

$I_C = f(V_{CE})$



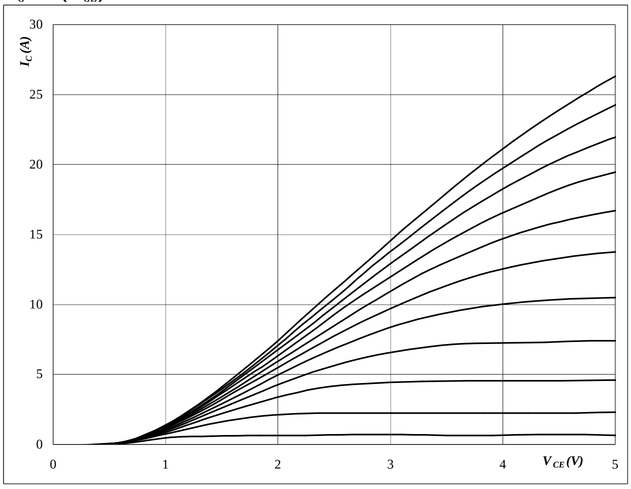
At

t_p =	250	µs
T_j =	25	°C
V_{GE} from	7 V to 17 V in steps of 1 V	

Figure 2 Output inverter IGBT

Typical output characteristics

$I_C = f(V_{CE})$



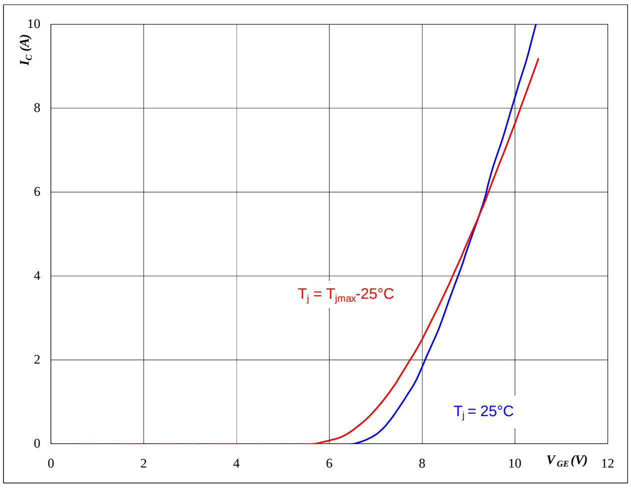
At

t_p =	250	µs
T_j =	125	°C
V_{GE} from	7 V to 17 V in steps of 1 V	

Figure 3 Output inverter IGBT

Typical transfer characteristics

$I_C = f(V_{GE})$



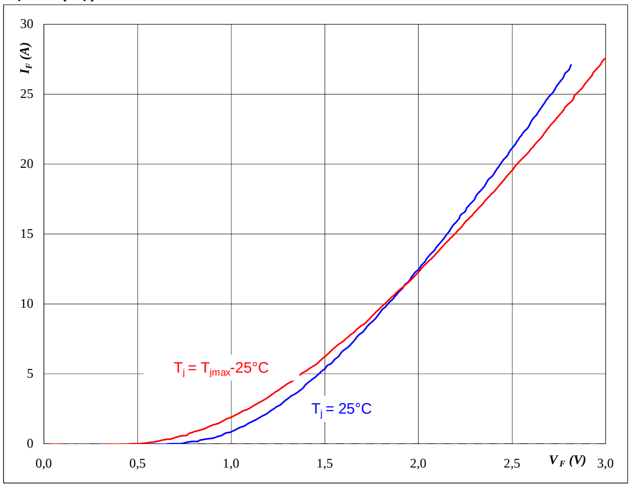
At

t_p =	250	µs
V_{CE} =	10	V

Figure 4 Output inverter FWD

Typical diode forward current as a function of forward voltage

$I_F = f(V_F)$



At

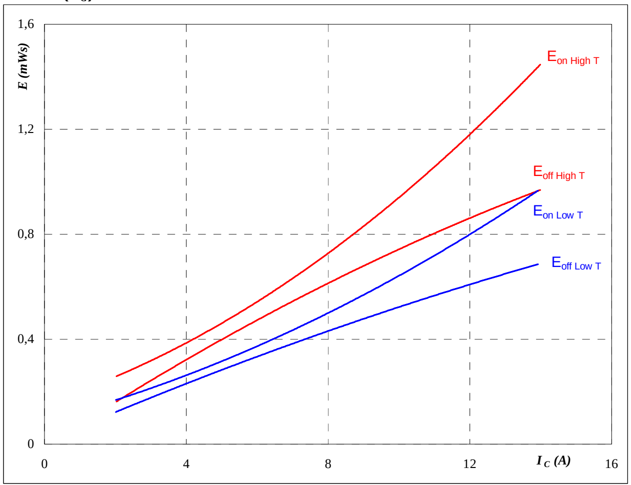
t_p =	250	µs

Output Inverter

Figure 5 Output inverter IGBT

Typical switching energy losses as a function of collector current

$E = f(I_C)$



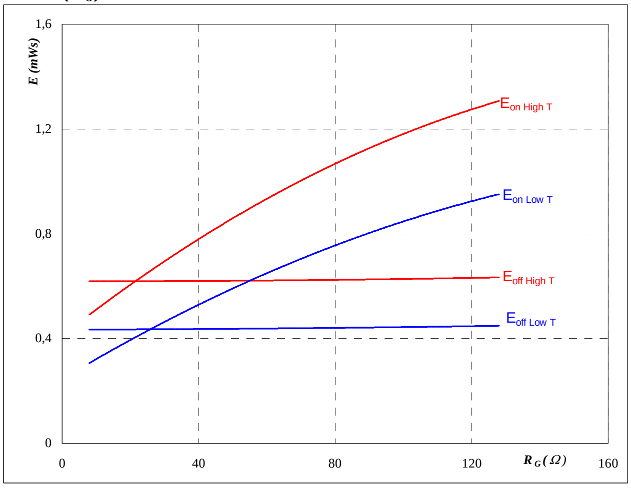
With an inductive load at

T_j =	25/125	°C
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	32	Ω
R_{goff} =	32	Ω

Figure 6 Output inverter IGBT

Typical switching energy losses as a function of gate resistor

$E = f(R_G)$



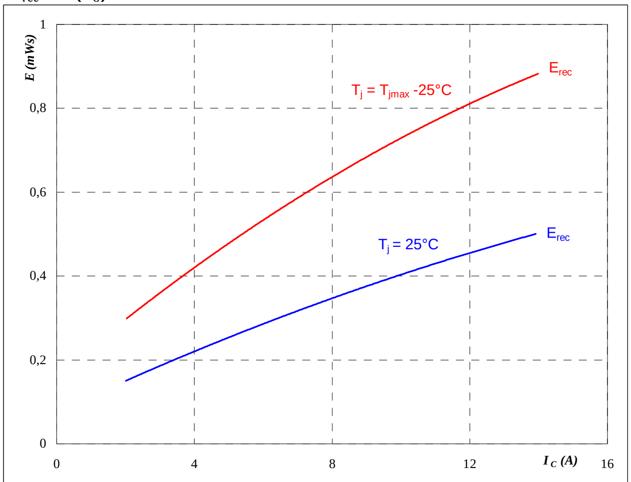
With an inductive load at

T_j =	25/125	°C
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	8	A

Figure 7 Output inverter FWD

Typical reverse recovery energy loss as a function of collector current

$E_{rec} = f(I_C)$



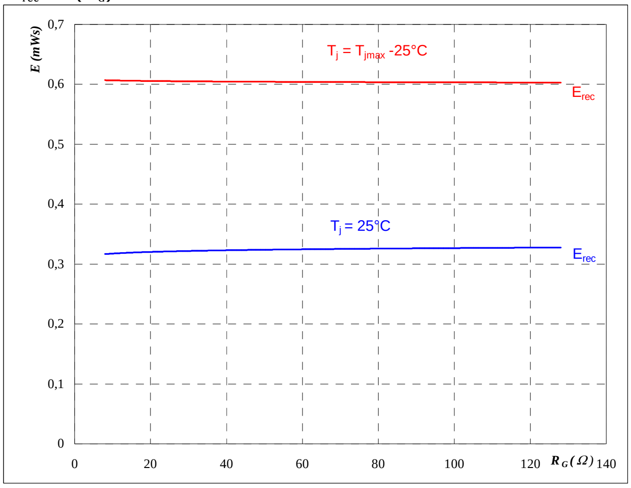
With an inductive load at

T_j =	25/125	°C
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	32	Ω

Figure 8 Output inverter FWD

Typical reverse recovery energy loss as a function of gate resistor

$E_{rec} = f(R_G)$



With an inductive load at

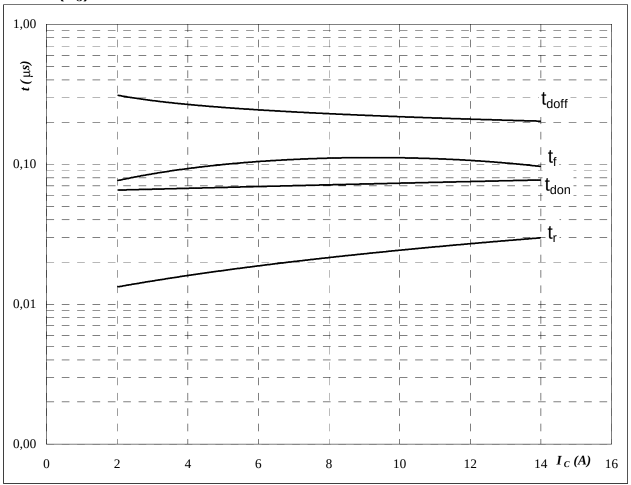
T_j =	25/125	°C
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	8	A

Output Inverter

Figure 9 Output inverter IGBT

Typical switching times as a function of collector current

$t = f(I_C)$



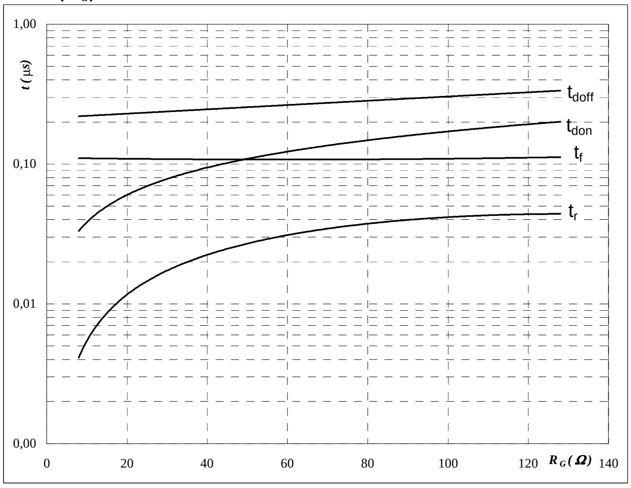
With an inductive load at

T_j =	125	°C
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	32	Ω
R_{goff} =	32	Ω

Figure 10 Output inverter IGBT

Typical switching times as a function of gate resistor

$t = f(R_G)$



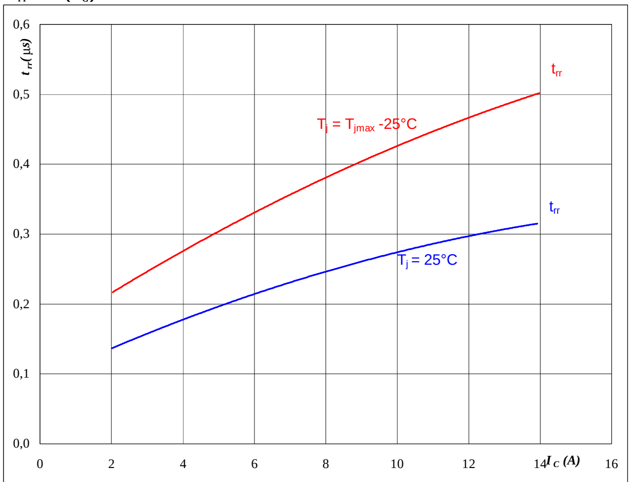
With an inductive load at

T_j =	125	°C
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	8	A

Figure 11 Output inverter FWD

Typical reverse recovery time as a function of collector current

$t_{rr} = f(I_C)$



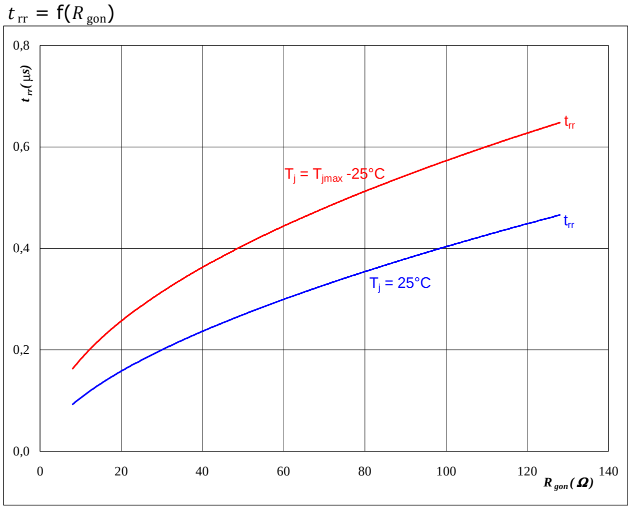
At

T_j =	25/125	°C
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	32	Ω

Figure 12 Output inverter FWD

Typical reverse recovery time as a function of IGBT turn on gate resistor

$t_{rr} = f(R_{gon})$



At

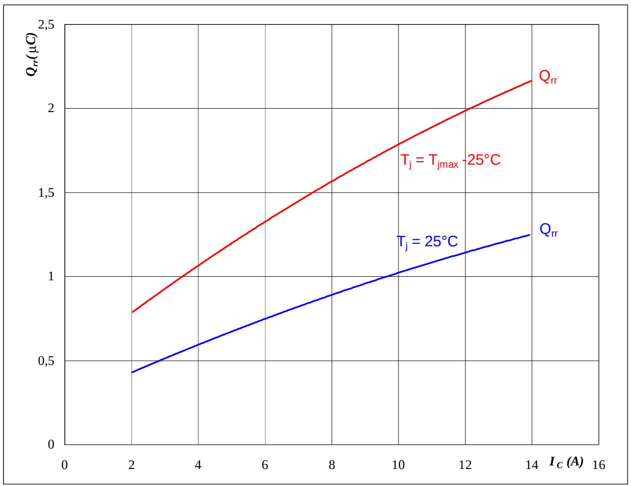
T_j =	25/125	°C
V_R =	600	V
I_F =	8	A
V_{GE} =	±15	V

Output Inverter

Figure 13 Output inverter FWD

Typical reverse recovery charge as a function of collector current

$Q_{rr} = f(I_C)$



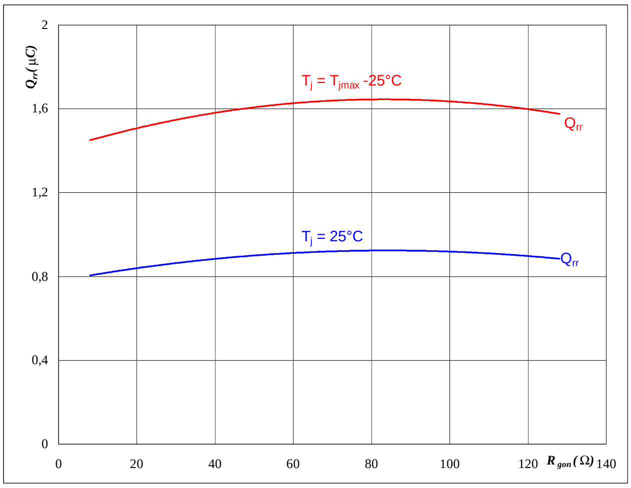
At

T_j = 25/125 °C
V_{CE} = 600 V
V_{GE} = ±15 V
R_{gon} = 32 Ω

Figure 14 Output inverter FWD

Typical reverse recovery charge as a function of IGBT turn on gate resistor

$Q_{rr} = f(R_{gon})$



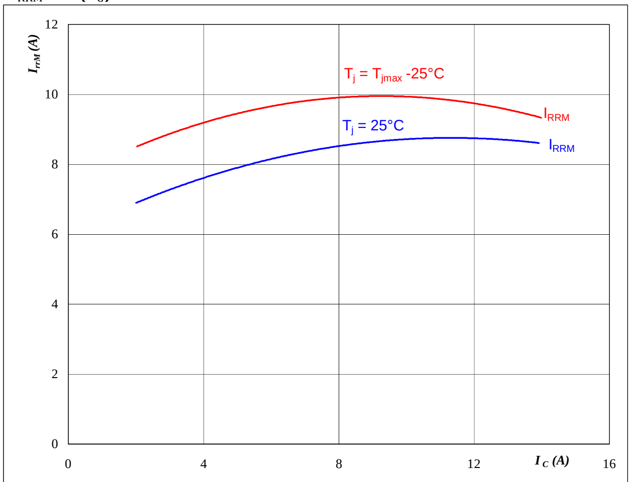
At

T_j = 25/125 °C
V_R = 600 V
I_F = 8 A
V_{GE} = ±15 V

Figure 15 Output inverter FWD

Typical reverse recovery current as a function of collector current

$I_{RRM} = f(I_C)$



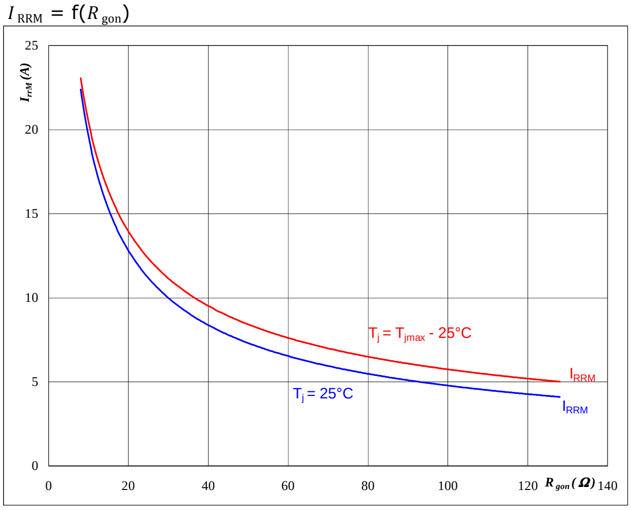
At

T_j = 25/125 °C
V_{CE} = 600 V
V_{GE} = ±15 V
R_{gon} = 32 Ω

Figure 16 Output inverter FWD

Typical reverse recovery current as a function of IGBT turn on gate resistor

$I_{RRM} = f(R_{gon})$



At

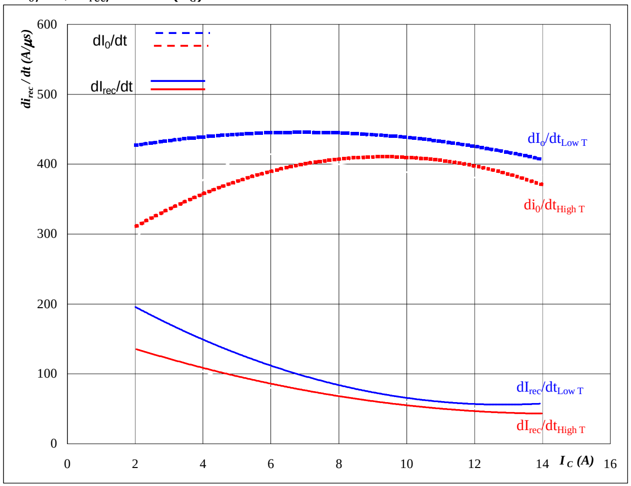
T_j = 25/125 °C
V_R = 600 V
I_F = 8 A
V_{GE} = ±15 V

Output Inverter

Figure 17 Output inverter FWD

Typical rate of fall of forward and reverse recovery current as a function of collector current

$dI_0/dt, dI_{rec}/dt = f(I_C)$



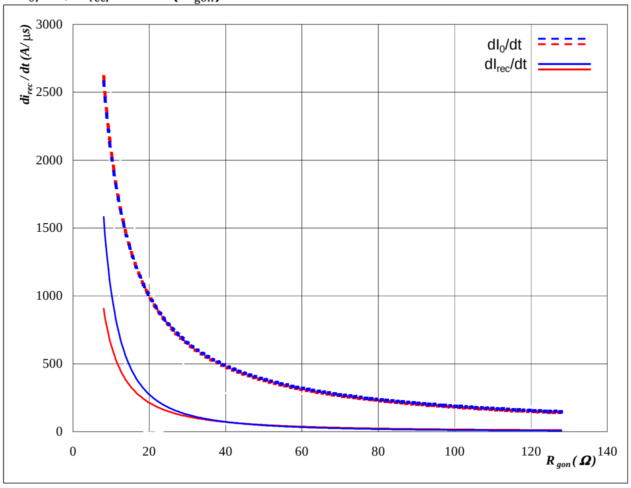
At

T_j =	25/125	°C
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	32	Ω

Figure 18 Output inverter FWD

Typical rate of fall of forward and reverse recovery current as a function of IGBT turn on gate resistor

$dI_0/dt, dI_{rec}/dt = f(R_{gon})$



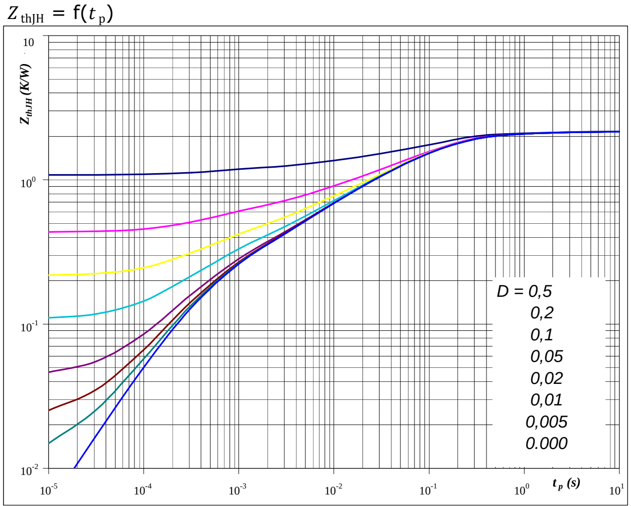
At

T_j =	25/125	°C
V_R =	600	V
I_F =	8	A
V_{GE} =	±15	V

Figure 19 Output inverter IGBT

IGBT transient thermal impedance as a function of pulse width

$Z_{thJH} = f(t_p)$



At

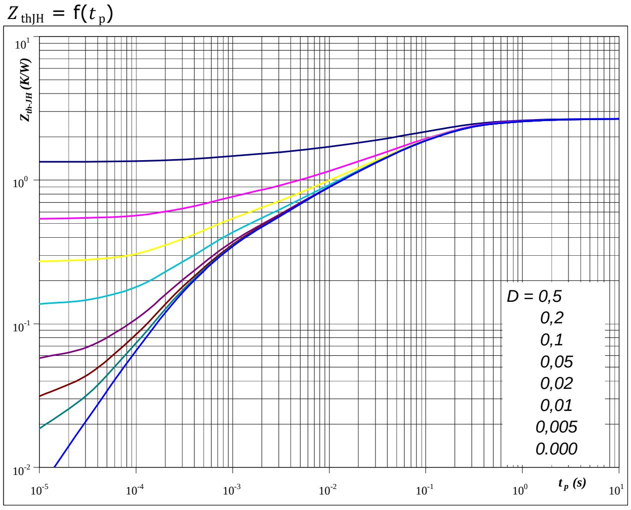
D = t_p / T

R_{thJH} = 2,16 K/W R_{thJH} = 1,86 K/W

Figure 20 Output inverter FWD

FWD transient thermal impedance as a function of pulse width

$Z_{thJH} = f(t_p)$



At

D = t_p / T

R_{thJH} = 2,68 K/W R_{thJH} = 2,33 K/W

IGBT thermal model values

Thermal grease R (K/W)	Thermal grease Tau (s)	Phase change material R (K/W)	Phase change material Tau (s)
0,05	4,1E+00	0,04	4,1E+00
0,25	5,5E-01	0,21	5,5E-01
0,99	1,0E-01	0,85	1,0E-01
0,45	1,9E-02	0,39	1,9E-02
0,24	3,3E-03	0,21	3,3E-03
0,18	4,0E-04	0,16	4,0E-04

FWD thermal model values

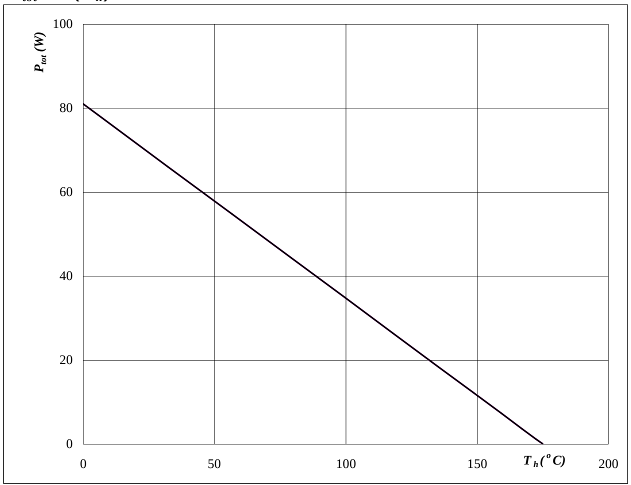
Thermal grease R (K/W)	Thermal grease Tau (s)	Phase change material R (K/W)	Phase change material Tau (s)
0,05	7,9E+00	0,04	7,9E+00
0,27	7,3E-01	0,23	7,3E-01
1,07	1,3E-01	0,92	1,3E-01
0,69	2,5E-02	0,59	2,5E-02
0,36	3,6E-03	0,31	3,6E-03
0,25	4,3E-04	0,21	4,3E-04

Output Inverter

Figure 21	Output inverter IGBT

Power dissipation as a function of heatsink temperature

$P_{tot} = f(T_h)$



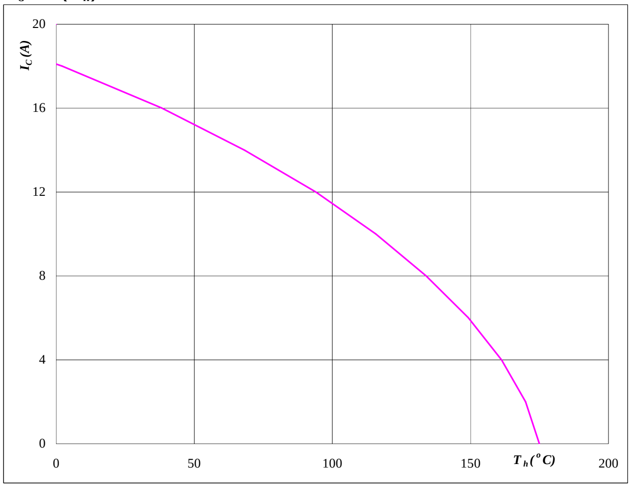
At

T_j = 175 °C

Figure 22	Output inverter IGBT

Collector current as a function of heatsink temperature

$I_C = f(T_h)$



At

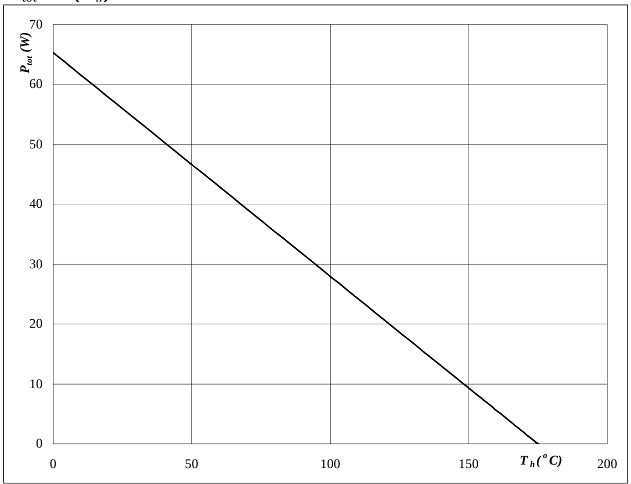
T_j = 175 °C

V_{GE} = 15 V

Figure 23	Output inverter FWD

Power dissipation as a function of heatsink temperature

$P_{tot} = f(T_h)$



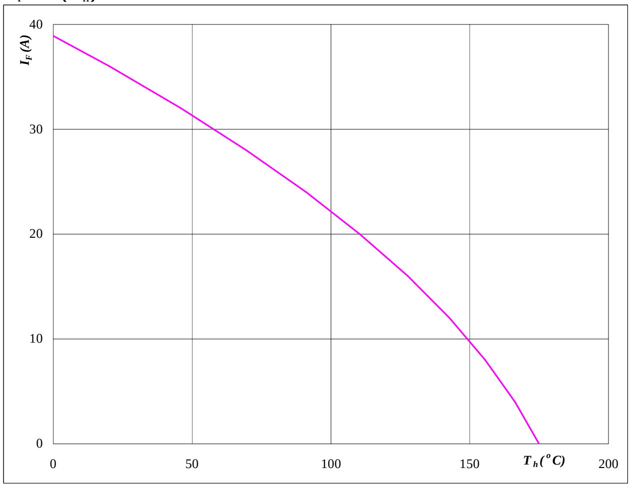
At

T_j = 175 °C

Figure 24	Output inverter FWD

Forward current as a function of heatsink temperature

$I_F = f(T_h)$



At

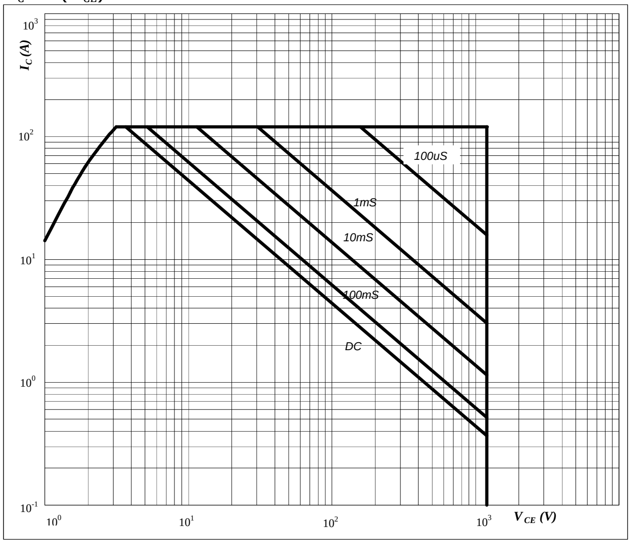
T_j = 175 °C

Output Inverter

Figure 25 Output inverter IGBT

Safe operating area as a function of collector-emitter voltage

$I_C = f(V_{CE})$



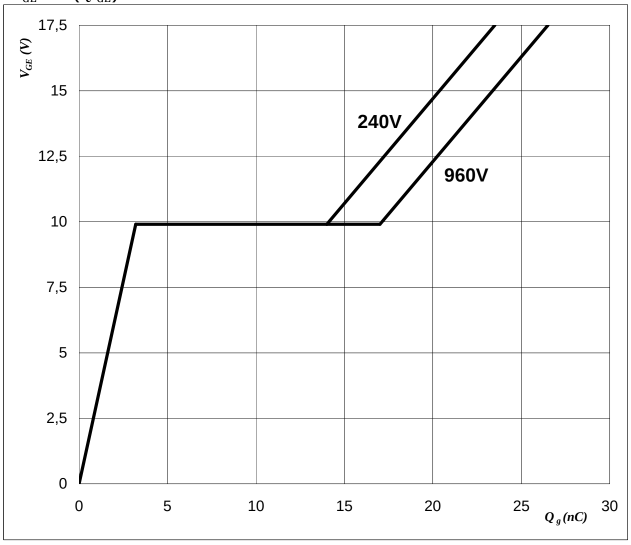
At

D =	single pulse	
T_h =	80	ºC
V_{GE} =	±15	V
T_j =	T_{jmax}	ºC

Figure 26 Output inverter IGBT

Gate voltage vs Gate charge

$V_{GE} = f(Q_{GE})$



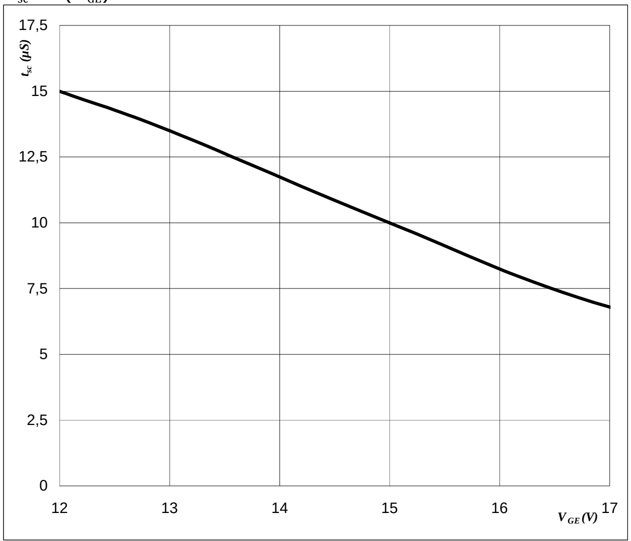
At

I_C =	8	A

Figure 27 Output inverter IGBT

Short circuit withstand time as a function of gate-emitter voltage

$t_{sc} = f(V_{GE})$



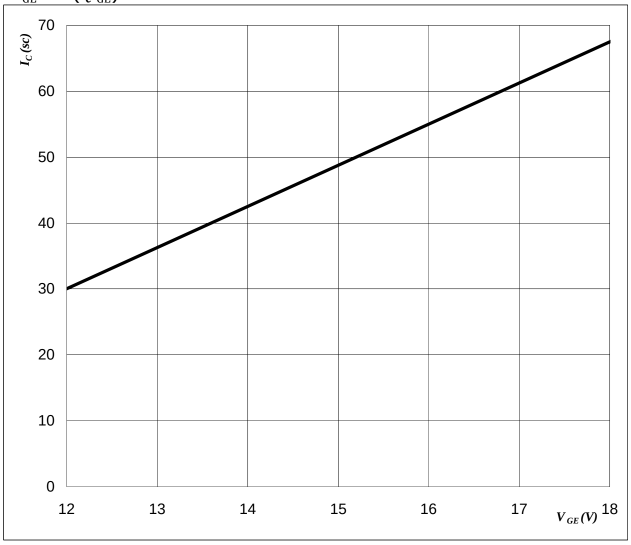
At

V_{CE} =	1200	V
T_j ≤	175	ºC

Figure 28 Output inverter IGBT

Typical short circuit collector current as a function of gate-emitter voltage

$V_{GE} = f(Q_{GE})$



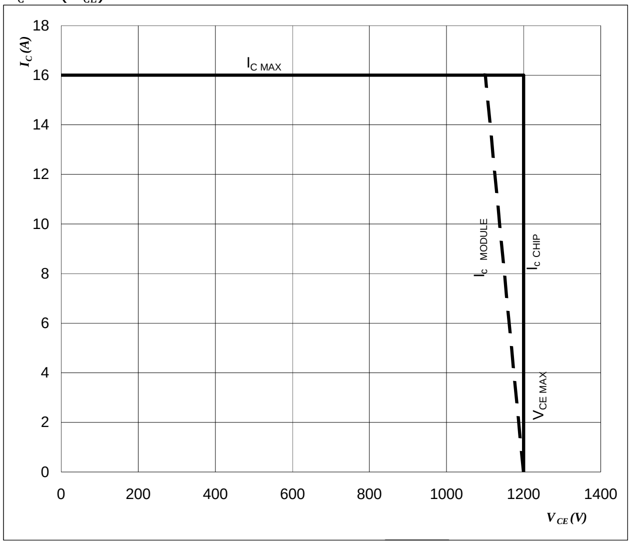
At

V_{CE} ≤	1200	V
T_j =	175	ºC

Figure 29 Output inverter IGBT

Reverse bias safe operating area

$I_C = f(V_{CE})$



At

T_j = T_{jmax}-25 ºC

Uccminus=Uccplus

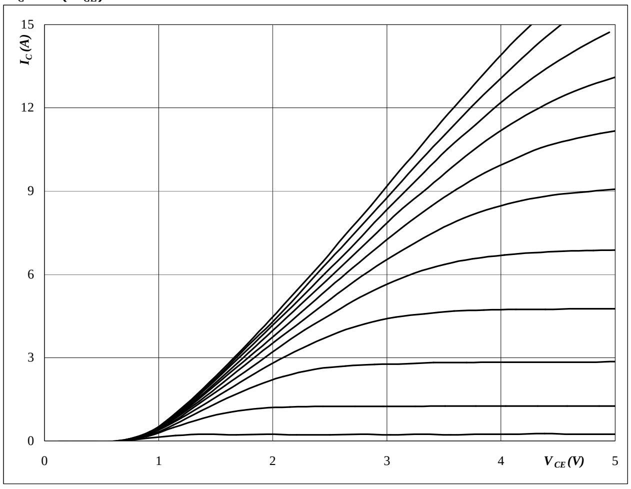
Switching mode : 3 level switching

Brake

Figure 1 Brake IGBT

Typical output characteristics

I_C = f(V_{CE})



At

t_p = 250 µs

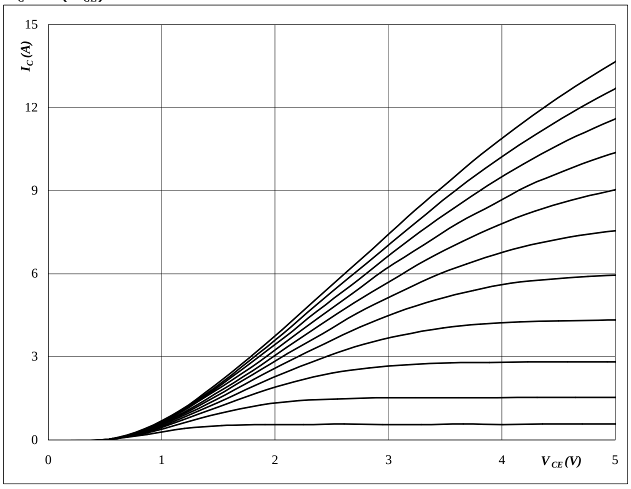
T_j = 25 °C

V_{GE} from 7 V to 17 V in steps of 1 V

Figure 2 Brake IGBT

Typical output characteristics

I_C = f(V_{CE})



At

t_p = 250 µs

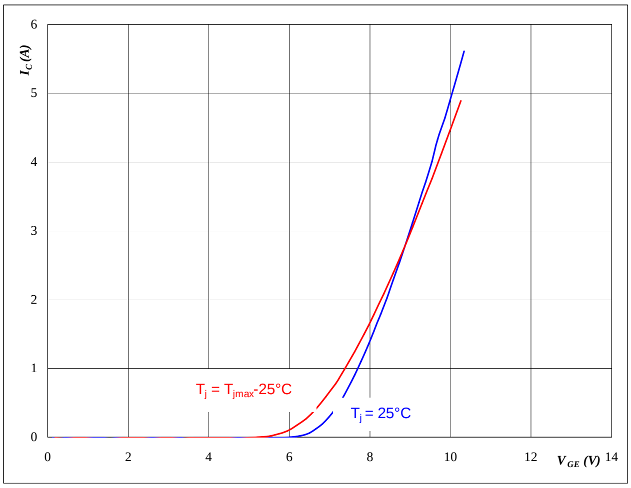
T_j = 125 °C

V_{GE} from 7 V to 17 V in steps of 1 V

Figure 3 Brake IGBT

Typical transfer characteristics

I_C = f(V_{GE})



At

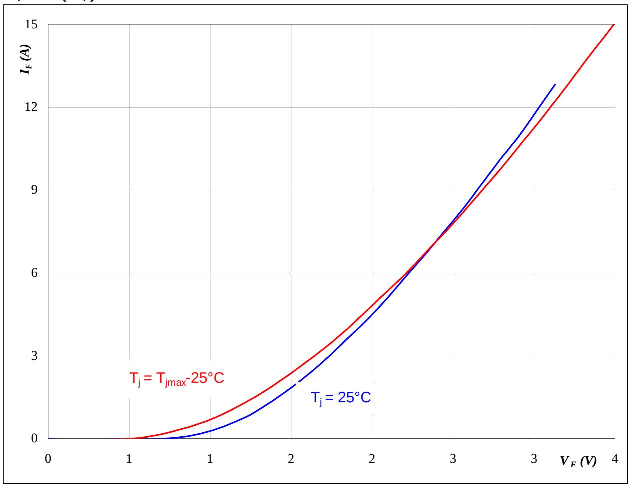
t_p = 250 µs

V_{CE} = 10 V

Figure 4 Brake FWD

Typical diode forward current as a function of forward voltage

I_F = f(V_F)



At

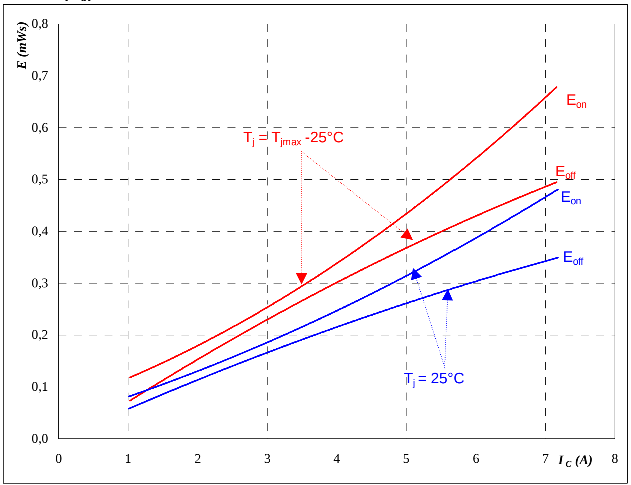
t_p = 250 µs

Brake

Figure 5 Brake IGBT

Typical switching energy losses as a function of collector current

$E = f(I_C)$



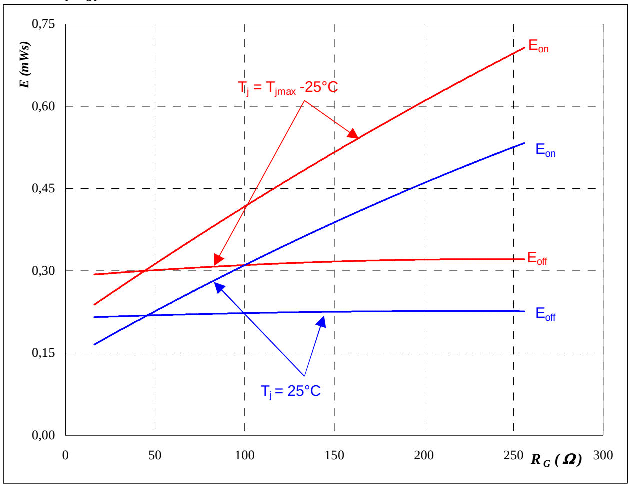
With an inductive load at

T_j =	25/125	°C
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	64	Ω
R_{goff} =	64	Ω

Figure 6 Brake IGBT

Typical switching energy losses as a function of gate resistor

$E = f(R_G)$



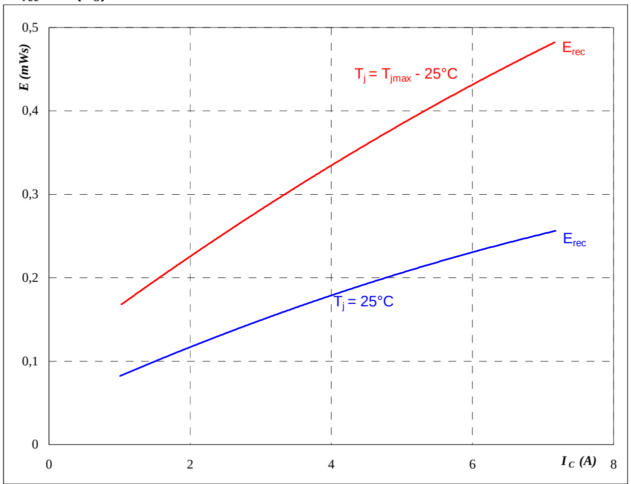
With an inductive load at

T_j =	25/125	°C
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	4	A

Figure 7 Brake FWD

Typical reverse recovery energy loss as a function of collector current

$E_{rec} = f(I_C)$



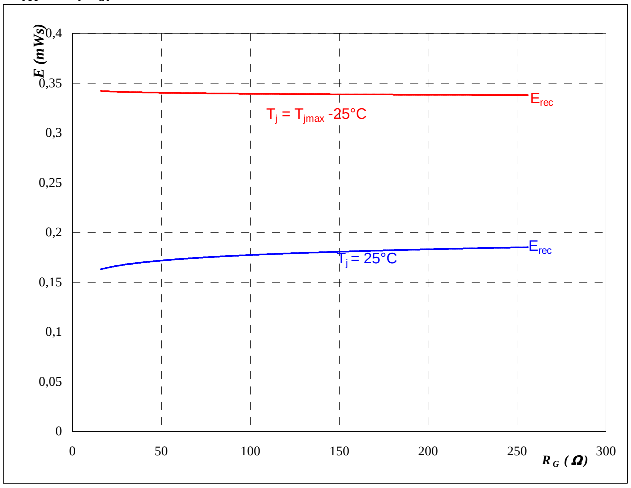
With an inductive load at

T_j =	25/125	°C
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	64	Ω

Figure 8 Brake FWD

Typical reverse recovery energy loss as a function of gate resistor

$E_{rec} = f(R_G)$



With an inductive load at

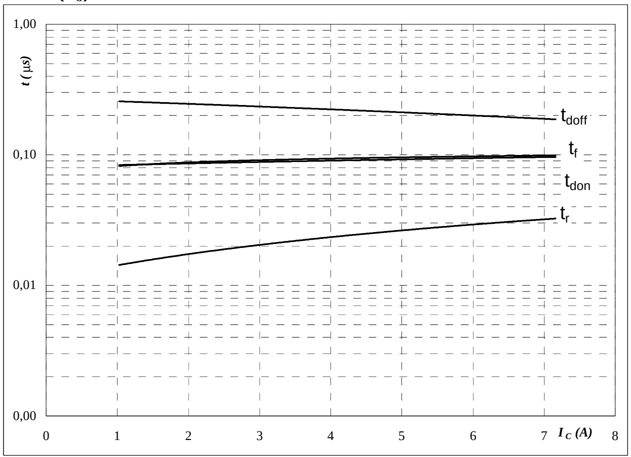
T_j =	25/125	°C
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	4	A

Brake

Figure 9	Brake IGBT

Typical switching times as a function of collector current

$t = f(I_C)$



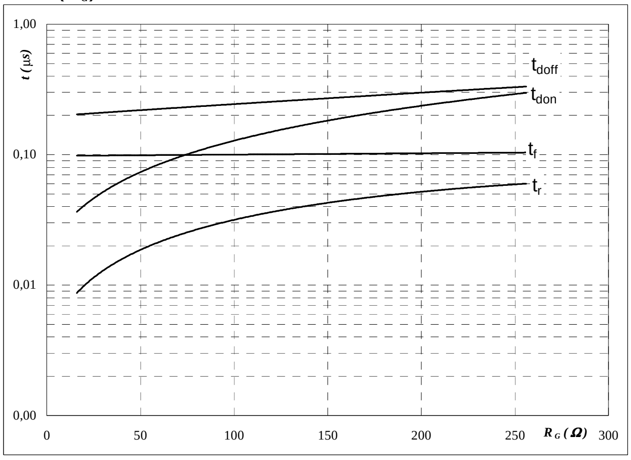
With an inductive load at

T_j =	125	°C
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	64	Ω
R_{goff} =	64	Ω

Figure 10	Brake IGBT

Typical switching times as a function of gate resistor

$t = f(R_G)$



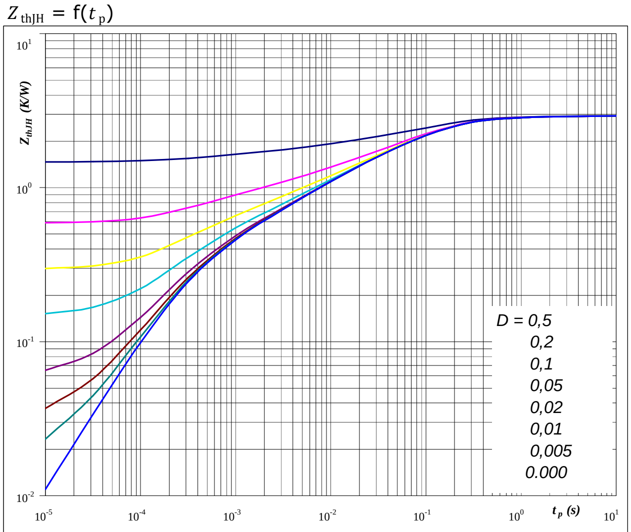
With an inductive load at

T_j =	125	°C
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	4	A

Figure 11	Brake IGBT

IGBT transient thermal impedance as a function of pulse width

$Z_{thJH} = f(t_p)$

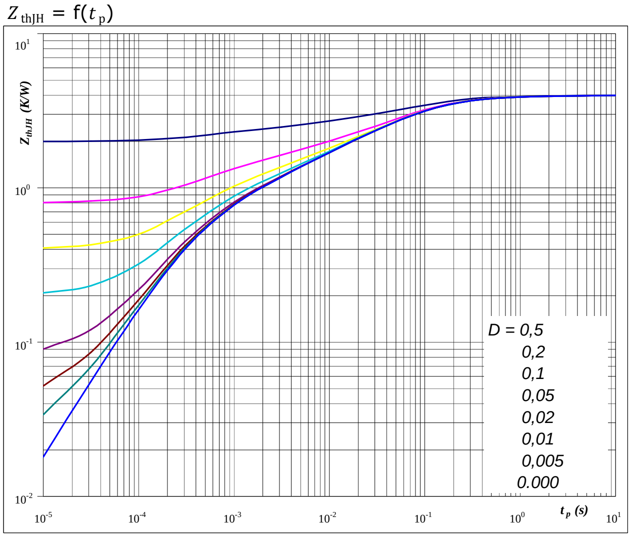


At		D =	t_p / T		
Thermal grease			Phase change material		
R_{thJH} =	2,93	K/W	R_{thJH} =	2,55	K/W

Figure 12	Brake FWD

FWD transient thermal impedance as a function of pulse width

$Z_{thJH} = f(t_p)$



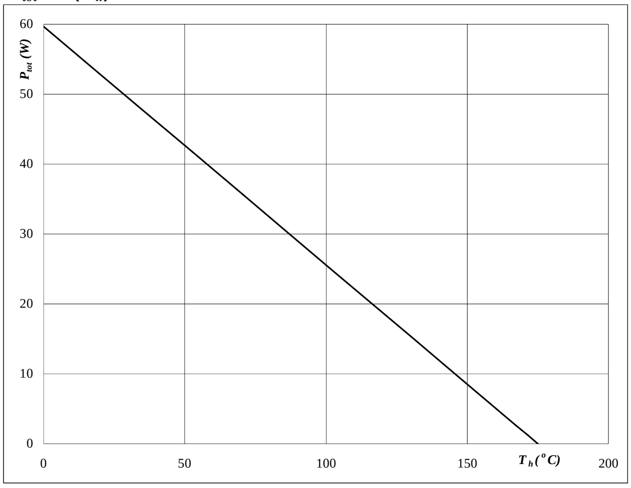
At		D =	t_p / T		
Thermal grease			Phase change material		
R_{thJH} =	3,98	K/W	R_{thJH} =	3,49	K/W

Brake

Figure 13 Brake IGBT

Power dissipation as a function of heatsink temperature

$P_{tot} = f(T_h)$



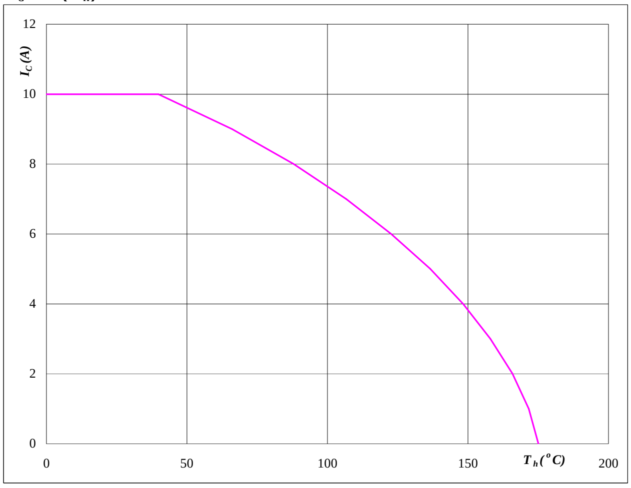
At

T_j = 175 ºC

Figure 14 Brake IGBT

Collector current as a function of heatsink temperature

$I_C = f(T_h)$



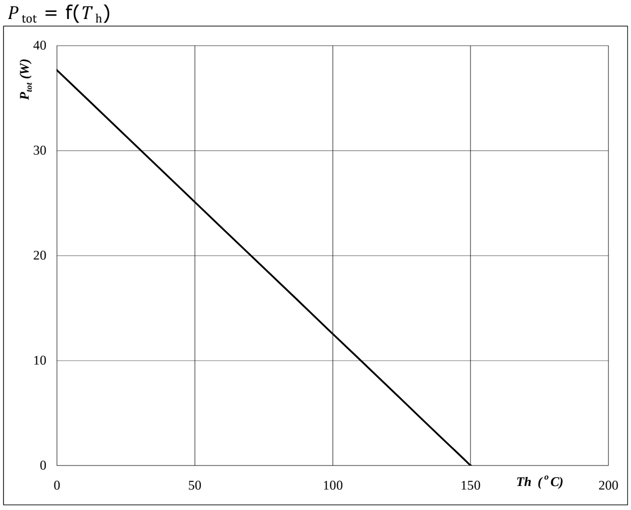
At

T_j = 175 ºC
V_{GE} = 15 V

Figure 15 Brake FWD

Power dissipation as a function of heatsink temperature

$P_{tot} = f(T_h)$



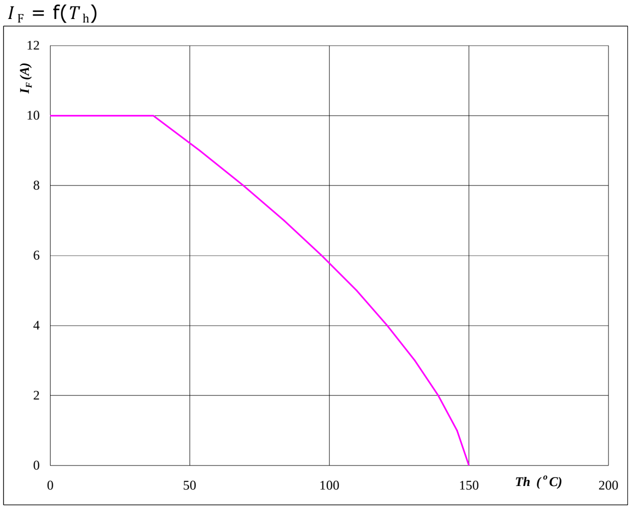
At

T_j = 150 ºC

Figure 16 Brake FWD

Forward current as a function of heatsink temperature

$I_F = f(T_h)$



At

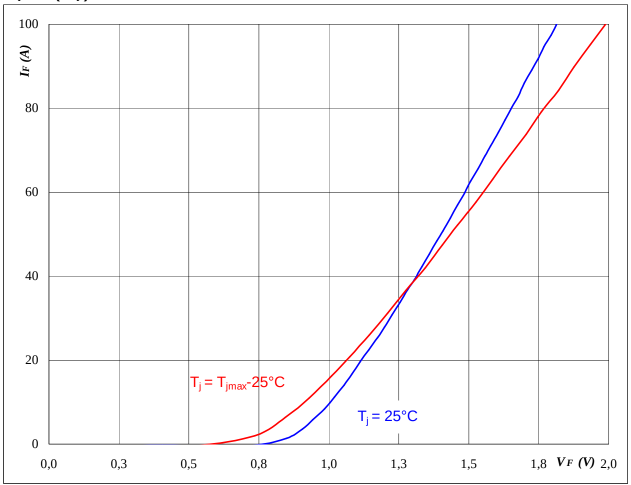
T_j = 150 ºC

Input Rectifier Bridge

Figure 1	Rectifier diode

Typical diode forward current as a function of forward voltage

$I_F = f(V_F)$



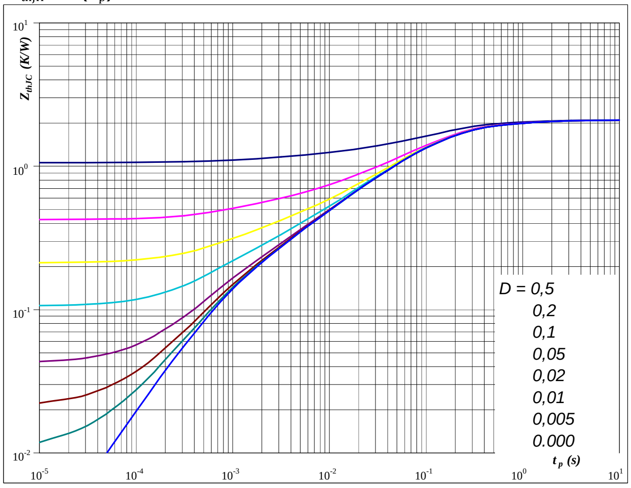
At

t_p = 250 µs

Figure 2	Rectifier diode

Diode transient thermal impedance as a function of pulse width

$Z_{thJH} = f(t_p)$



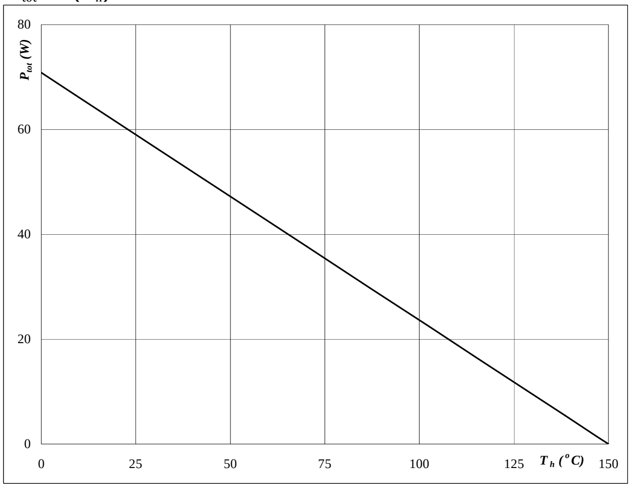
At D = t_p / T

Thermal grease			Phase change material		
D =	t_p / T		D =	t_p / T	
R_{thJH} =	2,13	K/W	R_{thJH} =	1,84	K/W

Figure 3	Rectifier diode

Power dissipation as a function of heatsink temperature

$P_{tot} = f(T_h)$



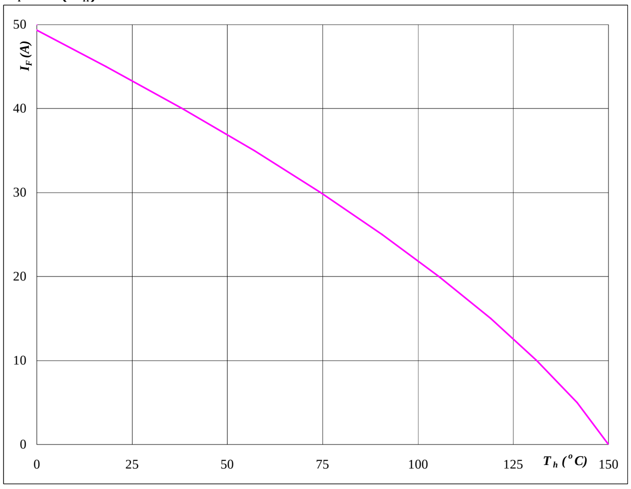
At

T_j = 150 ºC

Figure 4	Rectifier diode

Forward current as a function of heatsink temperature

$I_F = f(T_h)$



At

T_j = 150 ºC

Thermistor

Figure 1 Thermistor

Typical NTC characteristic
as a function of temperature
$R_T = f(T)$

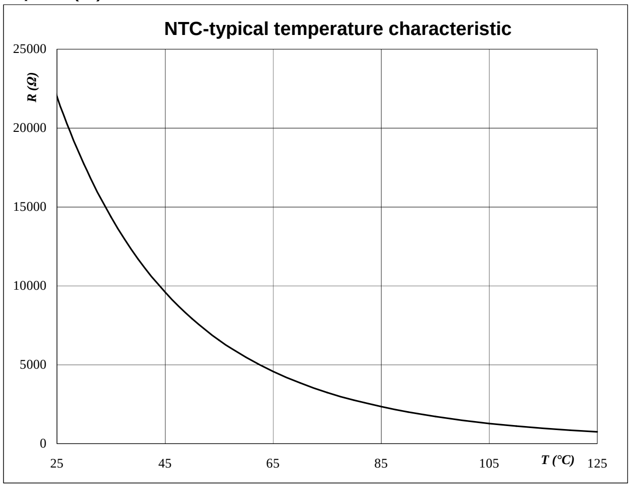


Figure 2 Thermistor

Typical NTC resistance values

$$R(T) = R_{25} \cdot e^{\left(B_{25/100}\left(\frac{1}{T} - \frac{1}{T_{25}}\right)\right)} \quad [\Omega]$$

T [°C]	R_{nom} [Ω]	R_{min} [Ω]	R_{max} [Ω]	△R/R [±%]
-55	2089434,5	1506495,4	2672373,6	27,9
0	71804,2	59724,4	83884	16,8
10	43780,4	37094,4	50466,5	15,3
20	27484,6	23684,6	31284,7	13,8
25	22000	19109,3	24890,7	13,1
30	17723,3	15512,2	19934,4	12,5
60	5467,9	4980,6	5955,1	8,9
70	3848,6	3546	4151,1	7,9
80	2757,7	2568,2	2947,1	6,9
90	2008,9	1889,7	2128,2	5,9
100	**1486,1**	**1411,8**	**1560,4**	**5**
150	400,2	364,8	435,7	8,8

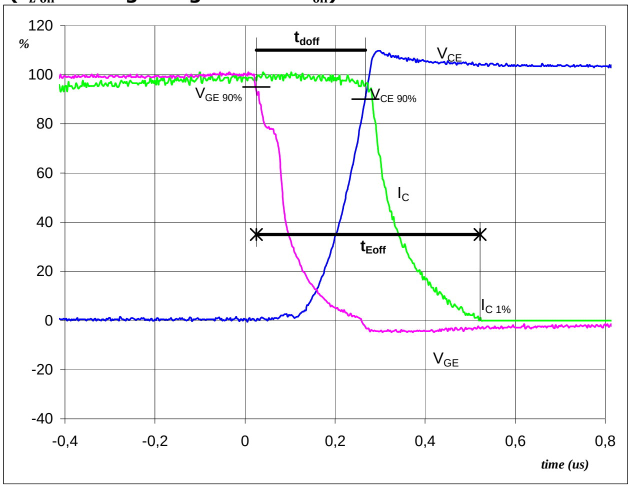
Switching Definitions Output Inverter

General conditions

T_j	=	125 °C
R_{gon}	=	32 Ω
R_{goff}	=	32 Ω

Figure 1 Output inverter IGBT

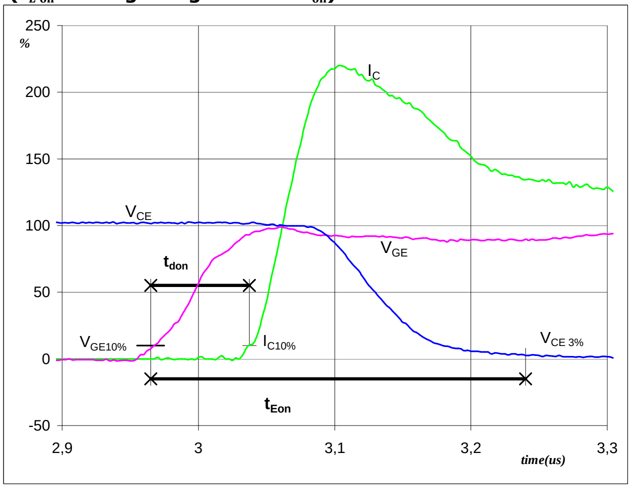
Turn-off Switching Waveforms & definition of t_{doff}, t_{Eoff}
($t_{E\,off}$ = integrating time for E_{off})



V_{GE} (0%) =	-15	V
V_{GE} (100%) =	15	V
V_C (100%) =	600	V
I_C (100%) =	8	A
t_{doff} =	0,24	μs
$t_{E\,off}$ =	0,50	μs

Figure 2 Output inverter IGBT

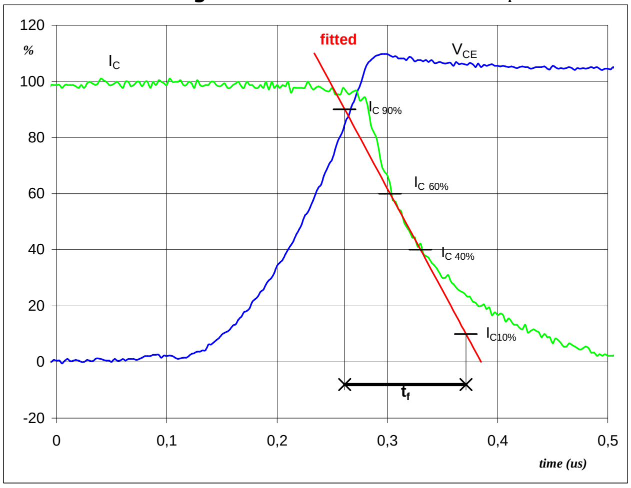
Turn-on Switching Waveforms & definition of t_{don}, t_{Eon}
($t_{E\,on}$ = integrating time for E_{on})



V_{GE} (0%) =	-15	V
V_{GE} (100%) =	15	V
V_C (100%) =	600	V
I_C (100%) =	8	A
t_{don} =	0,07	μs
$t_{E\,on}$ =	0,27	μs

Figure 3 Output inverter IGBT

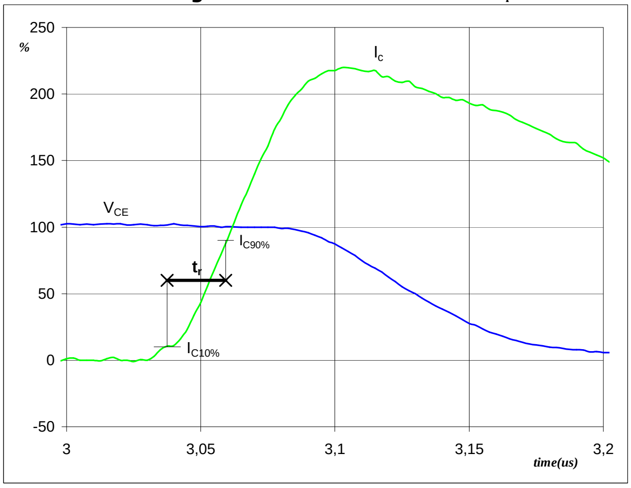
Turn-off Switching Waveforms & definition of t_f



V_C (100%) =	600	V
I_C (100%) =	8	A
t_f =	0,11	μs

Figure 4 Output inverter IGBT

Turn-on Switching Waveforms & definition of t_r

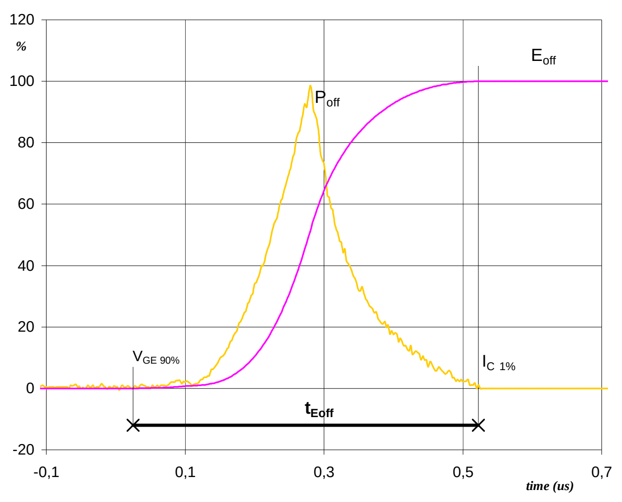


V_C (100%) =	600	V
I_C (100%) =	8	A
t_r =	0,02	μs

Switching Definitions Output Inverter

Figure 5 — Output inverter IGBT

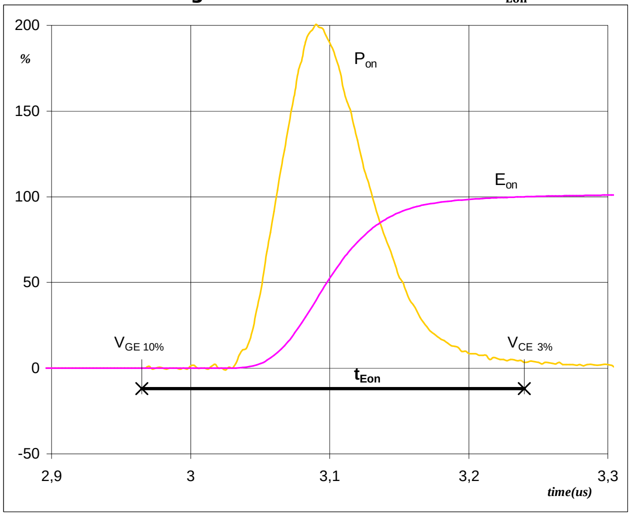
Turn-off Switching Waveforms & definition of t_{Eoff}



P_{off} (100%) =	4,93	kW
E_{off} (100%) =	0,62	mJ
$t_{E\,off}$ =	0,50	μs

Figure 6 — Output inverter IGBT

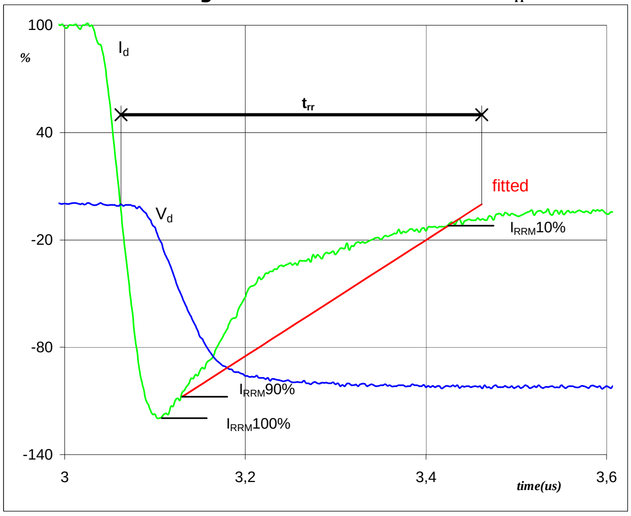
Turn-on Switching Waveforms & definition of t_{Eon}



P_{on} (100%) =	4,93	kW
E_{on} (100%) =	0,75	mJ
$t_{E\,on}$ =	0,27	μs

Figure 7 — Output inverter FWD

Turn-off Switching Waveforms & definition of t_{rr}

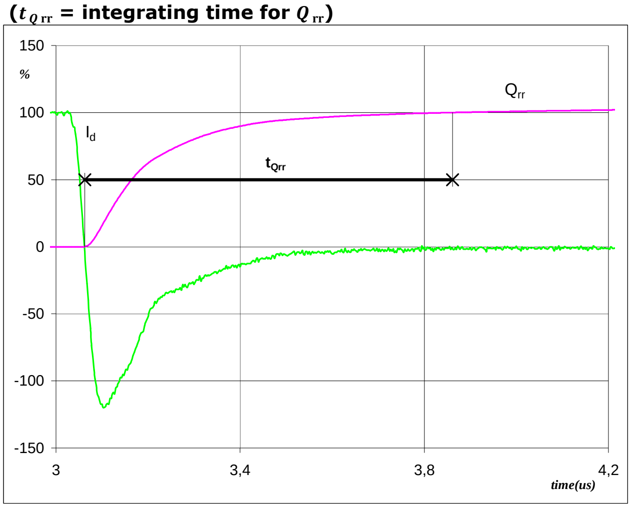


V_d (100%) =	600	V
I_d (100%) =	8	A
I_{RRM} (100%) =	-10	A
t_{rr} =	0,38	μs

Switching Definitions Output Inverter

Figure 8 Output inverter FWD

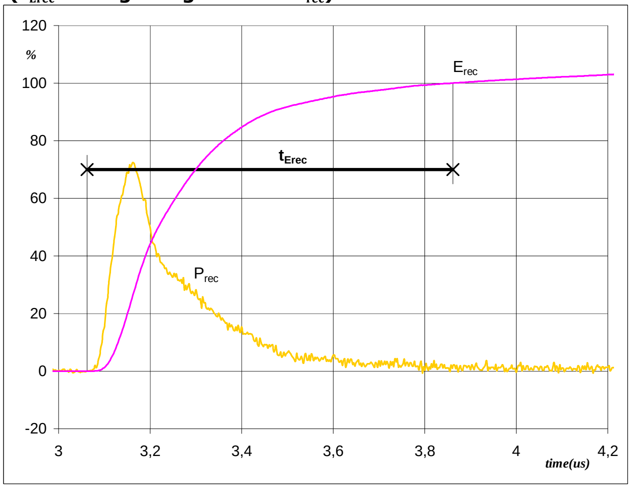
Turn-on Switching Waveforms & definition of t_{Qrr}
($t_{Q\,rr}$ = integrating time for Q_{rr})



I_d (100%) =	8	A
Q_{rr} (100%) =	1,57	µC
$t_{Q\,rr}$ =	0,80	µs

Figure 9 Output inverter FWD

Turn-on Switching Waveforms & definition of t_{Erec}
(t_{Erec}= integrating time for E_{rec})



P_{rec} (100%) =	4,93	kW
E_{rec} (100%) =	0,63	mJ
$t_{E\,rec}$ =	0,80	µs

Ordering Code and Marking - Outline

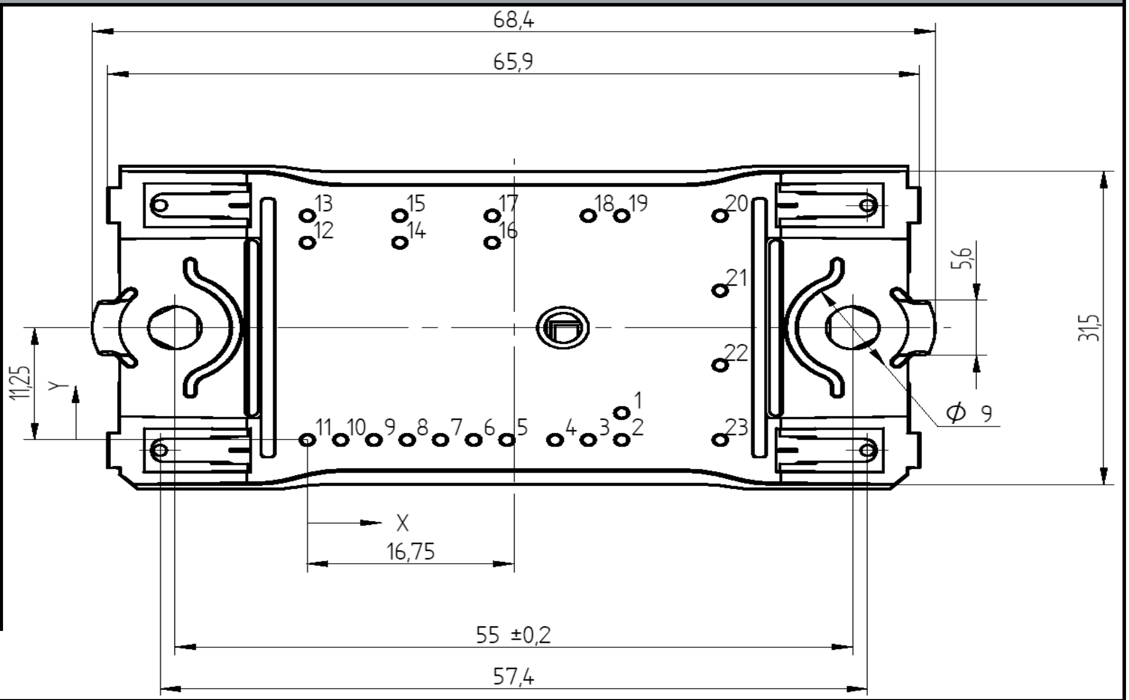
Ordering Code & Marking

Version	Ordering Code	in DataMatrix as	in packaging barcode as
without thermal paste 12mm housing with Solder pins ''A'' topology	V23990-P849-A48-PM	P849A48	P849A48
without thermal paste 12mm housing with Solder pins ''C'' topology	V23990-P849-C48-PM	P849C48	P849C48
without thermal paste 17mm housing with Solder pins "A" topology	V23990-P849-A49-PM	P849A49	P849A49
without thermal paste 17mm housing with Solder pins "C" topology	V23990-P849-C49-PM	P849C49	P849C49
without thermal paste 17mm housing with Press-fit pins "A" topology	V23990-P849-A49Y-PM	P849A49Y	P849A49Y
without thermal paste 17mm housing with Press-fit pins "C" topology	V23990-P849-C49Y-PM	P849C49Y	P849C49Y
without thermal paste 12mm housing with Press-fit pins "A" topology	V23990-P849-A48Y-PM	P849A48Y	P849A48Y
without thermal paste 12mm housing with Press-fit pins "C" topology	V23990-P849-C48Y-PM	P849C48Y	P849C48Y
with phase change material 12mm housing with Solder pins "A" topology	V23990-P849-A48-/3/-PM	P849A48	P849A48-/3/
with phase change material 12mm housing with Solder pins "C" topology	V23990-P849-C48-/3/-PM	P849C48	P849C48-/3/
with phase change material 17mm housing with Solder pins "A" topology	V23990-P849-A49-/3/-PM	P849A49	P849A49-/3/
with phase change material 17mm housing with Solder pins "C" topology	V23990-P849-C49-/3/-PM	P849C49	P849C49-/3/
with phase change material 17mm housing with Press-fit pins "A" topology	V23990-P849-A49Y-/3/-PM	P849A49Y	P849A49Y-/3/
with phase change material 17mm housing with Press-fit pins "C" topology	V23990-P849-C49Y-/3/-PM	P849C49Y	P849C49Y-/3/
with phase change material 12mm housing with Press-fit pins "A" topology	V23990-P849-A48Y-/3/-PM	P849A48Y	P849A48Y-/3/
with phase change material 12mm housing with Press-fit pins "C" topology	V23990-P849-C48Y-/3/-PM	P849C48Y	P849C48Y-/3/

Outline

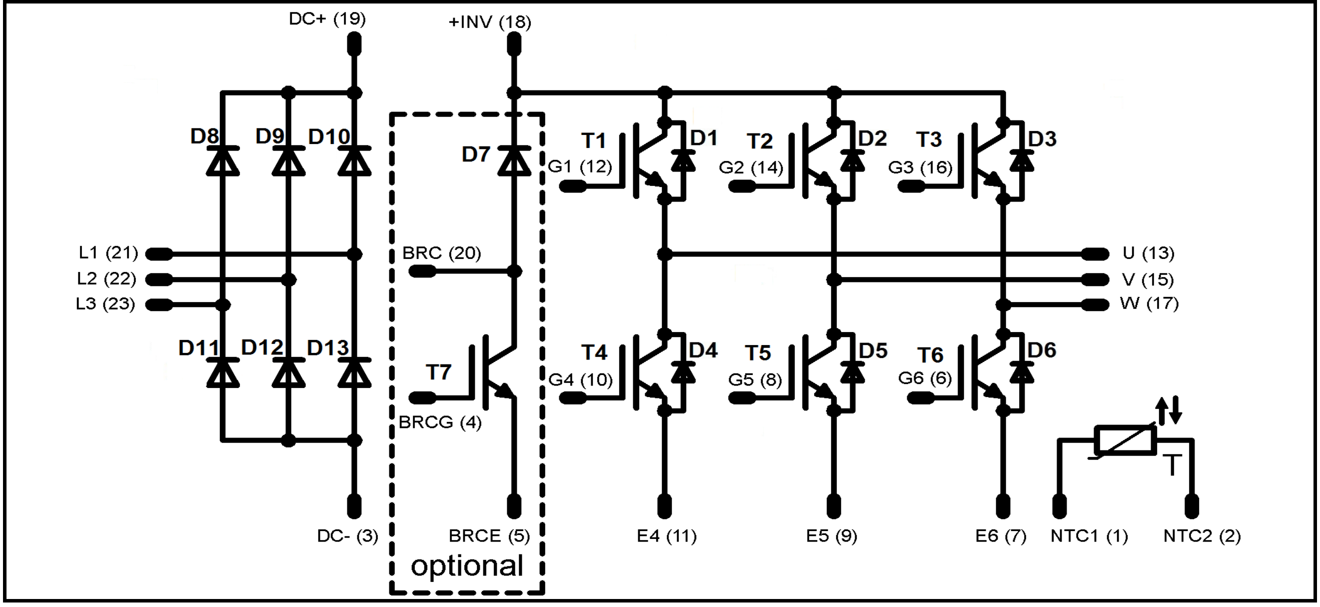
Pin table

Pin	X	Y
1	25,5	2,7
2	25,5	0
3	22,8	0
4	20,1	0
5	16,2	0
6	13,5	0
7	10,8	0
8	8,1	0
9	5,4	0
10	2,7	0
11	0	0
12	0	19,8
13	0	22,5
14	7,5	19,8
15	7,5	22,5
16	15	19,8
17	15	22,5
18	22,8	22,5
19	25,5	22,5
20	33,5	22,5
21	33,5	15
22	33,5	7,5
23	33,5	0



Pinout - Identification

Pinout



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Vincotech products are not authorised for use as critical components in life support devices or systems without the express written approval of Vincotech.

As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, or (c) whose failure to perform when properly used in accordance with instructions for use provided in labelling can be reasonably expected to result in significant injury to the user.

2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.